



Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT INFORMATION NOTIFICATION

PIN: PIN194304

Date: October 27, 2019

Subject: Qualification of Unimos Microelectronics as an Alternate Assembly Site for 8-Lead SOIC Package for FL-L and FS-S Product Families

To: TOKYO ELECTRON DEVICE
TELDEVICE
cy-inside@teldevice.co.jp

Change Type: Minor

Description of Change:

Cypress announces the qualification of 8-Lead SOIC package for FL-L and FS-S product families at Unimos Microelectronics (Unimos Microelectronics Co., Ltd. - 9688 Songze Ave., Qingpu Industrial Zone, Shanghai, China) as an alternate assembly site. Unimos Microelectronics is a world-class assembly facility, qualified to build standard and automotive grade products consistent with AEC-Q100/AEC-Q006 standards.

The current assembly site ZKT (Suzhou Zhen Kun Technology Limited - No.183, Fangzhou Road, Suzhou Industrial Park, Suzhou, China) using Samsung SG8500HKT/SG8300HKT mold compound has been EOL'd with short notice. Unimos Microelectronics is a Cypress qualified assembly site and has been shipping 8-Lead SOIC package for FL-P, FL-S, FL-1K and FL2-K product families since Q2'2010. Cypress is now extending Unimos Microelectronics as an alternate assembly site for 8-Lead SOIC with same BOM to FL-L, FS-S product families. This will enable Cypress to provide assembly operations to meet our customers' stringent quality and reliability requirements in our effort to continually provide world-class service.

FL-L and FS-S 8-Lead SOIC products assembled at Unimos Microelectronics will use the following Bill of Materials (BoM):

Material	ZKT Bill of Materials	Unimos Bill of Materials
Mold Compound	Samsung SG8500HKT/SG8300HKT	Hitachi CEL-9240
Lead Finish	Matte Sn	Matte Sn
Die Attach DAF	Yizbond 8511	Hitachi-4900 / Nitto EM710
Bond Wire	0.8mil PdCuAu	0.8mil PdCu

Benefit of Change:

Cypress will have the added capability to meet varying market demand, and to ensure consistent and reliable delivery performance to customers.

Part Numbers Affected: 41

See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PIN will include all changes outlined in this PIN.

Qualification Status:

This assembly site has been qualified for 8-SOIC Lead package for FL-L, FS-S product families through qualification by similarity based on full qualification of FL-P, FL-S, FL1-K, and FL2-K product families. Qualification Test Plan report QTP#194101 is found as an attachment to this PIN.

Approximate Implementation Date:

This change will be effective with the date of this notification.

Anticipated Impact:

No impact is expected to form, fit, function, datasheet parameters, package composition or package pin-out.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the date code marked on the package.

Response Required:

This is an information only announcement. No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration